

customer	
pcb name	
WE article number	
engineer	
date	



Multilayer 4 Layers

PCB Thickness : 2,10 mm +/- 10%

Rigid area Structure	Rigid area Thickness	Material description	Via types	Layer usage	Impedance	
					Er	Z[Ohm] Line / Space
Soldermask	15					
L1	45	* Incl. Plating	Top-Layer		3.5	
	230	FR4 TG 135			3.9	
L2	18					
	1480	FR4 TG 135			4.7	
L3	18					
	230	FR4 TG 135			3.9	
L4	45	* Incl. Plating	Bottom-Layer			
Soldermask	15				3.5	

Notes:

50 % copper occupancy IL

final copper thickness according to IPC 6012

Dielectric material according IPC-4101 E / 24

For Microvia technology please use our HDI stackups

Revision: Created: W. Brylka / Scrutinised: A. Schilpp / Approved: A.Schilpp

Template Revision: 06/2018 by Andreas Schilpp

Via types - Standard and options

